

AT1608 Series

Multilayer Chip Antenna

Features

- ❖ Monolithic SMD with small, low-profile and light-weight type.
- ❖ Wide bandwidth
- ❖ RoHS compliant



Applications

- ❖ 2400~2500MHz ISM Band Systems

Specifications

Part Number	Frequency Range (MHz)	Peak Gain (dBi typ.)	Average Gain (dBi typ.)	VSWR	Impedance
AT1608 -A2R4HAA_	2400~2480	-0.5 (XZ-total)	-2.0 (XZ-total)	3 max.	50 Ω

Q'ty/Reel (pcs) : 4,000 pcs
 Operating Temperature Range : -40 ~ +125 °C
 Storage Temperature Range : -40 ~ +85 °C
 Storage Period : 12 months max.
 Power Capacity : 2W max.

Part Number

AT 1608 - A 2R4 HAA □ □
 ① ② ③ ④ ⑤ ⑥ ⑦

① Type	AT : Antenna	② Dimensions (L x W)	1.6x 0.8 mm
③ Material Code	A	④ Frequency Range	2R4=2400MHz
⑤ Specification Code	HAA	⑥ Packaging	T: Tape & Reel B: Bulk
⑦ Soldering	/LF=lead-free		

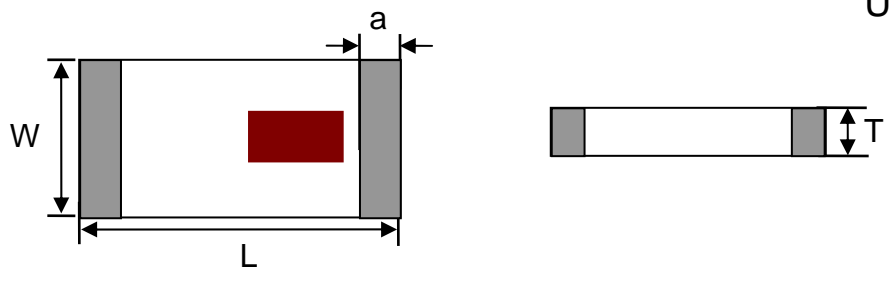
Terminal Configuration



No.	Terminal Name	No.	Terminal Name
①	Feeding Point	②	NC

Dimensions and Recommended PC Board Pattern

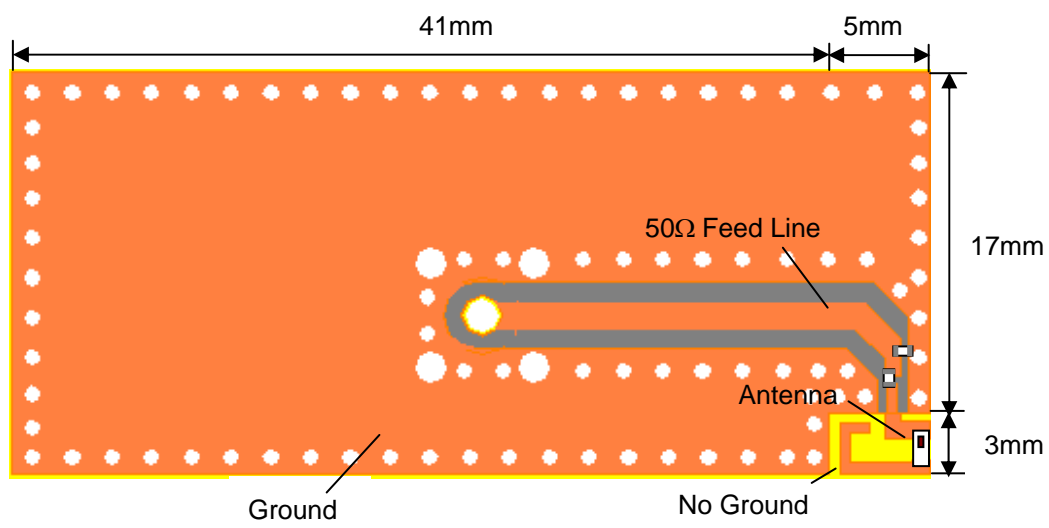
Unit : mm



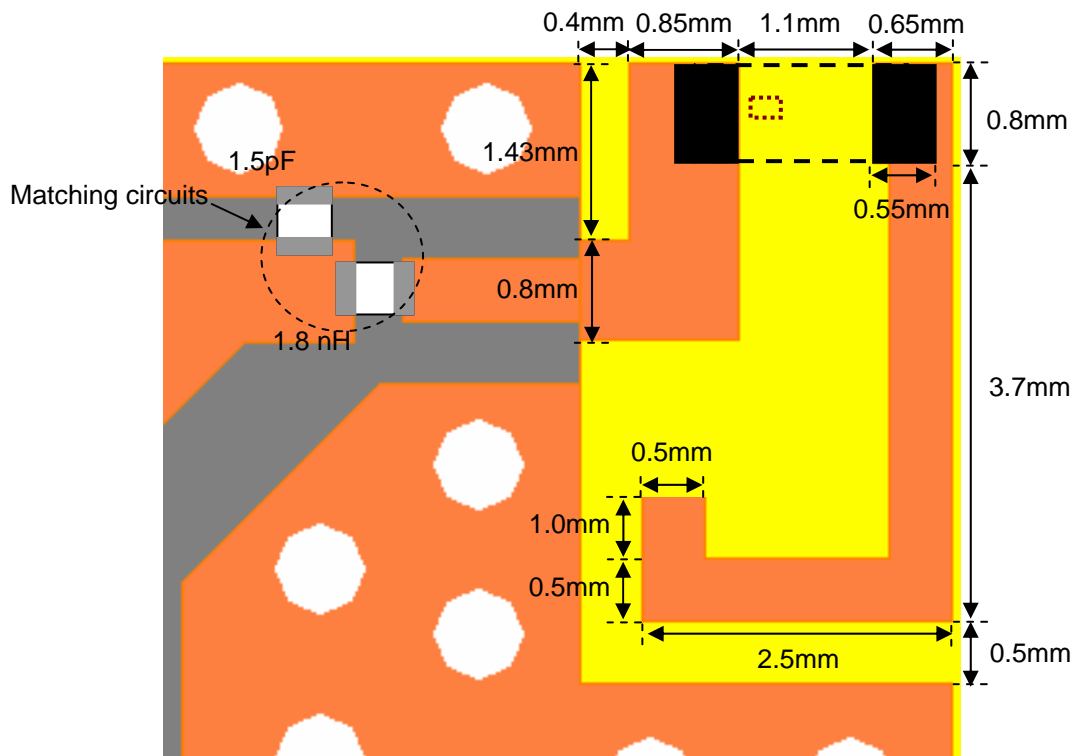
Mark	L	W	T	a
Dimensions	1.6 ± 0.1	0.8 ± 0.1	0.4 ± 0.1	0.25 ± 0.1

Typical Electrical Characteristics (T=25°C)

❖ Test Board-Type A



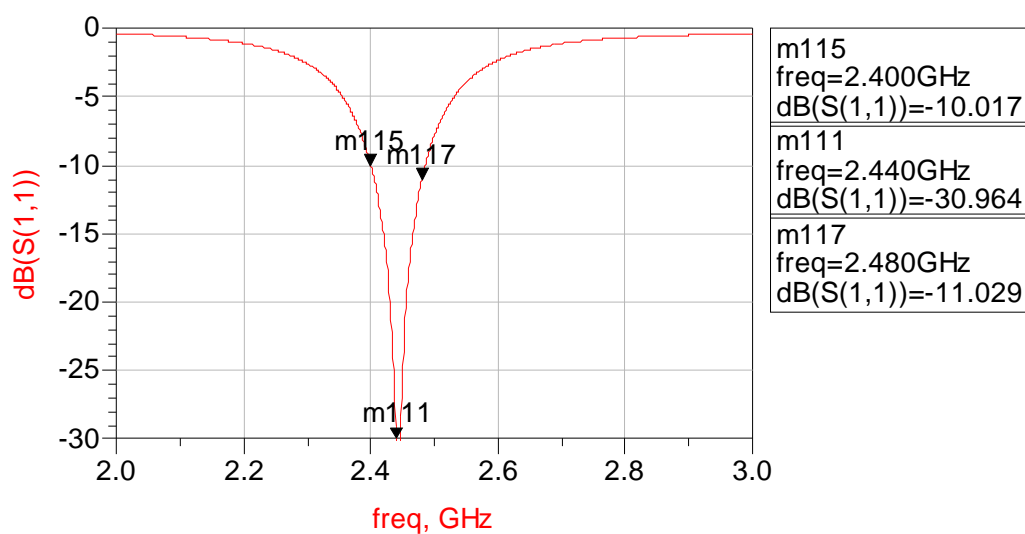
❖ Antenna Footprint with matching



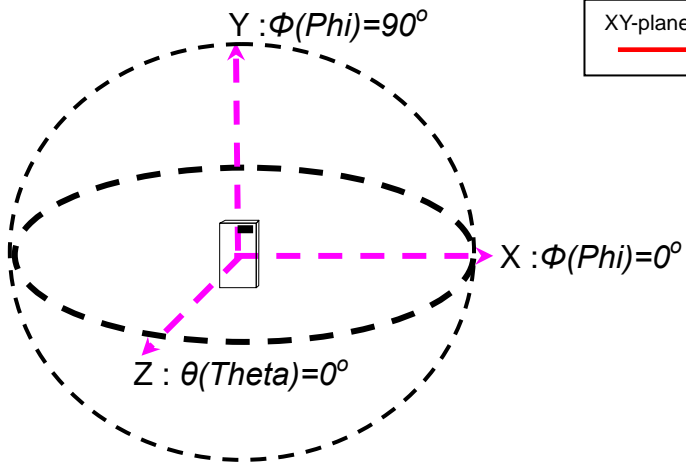
(Matching circuit and component values will be different, depending on PCB layout)

*Line width should be designed to match 50Ω characteristic impedance, depending on PCB material and thickness.

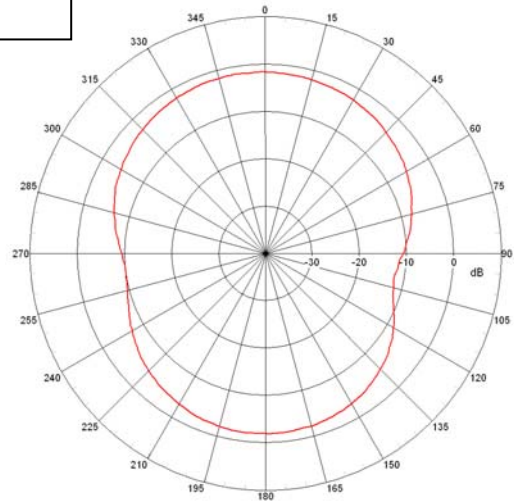
❖ Return Loss (with matching)



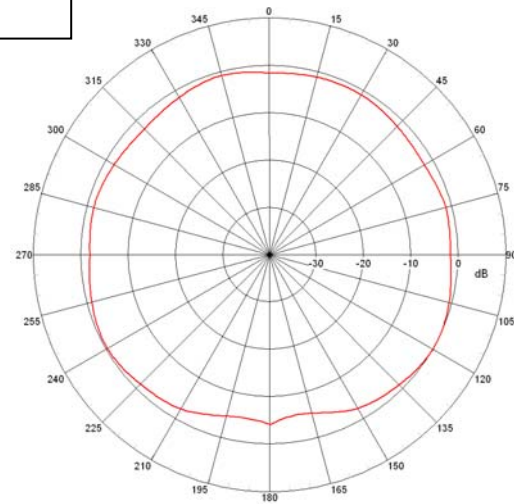
❖ Radiation Patterns- (Antenna Efficiency: 48 %)



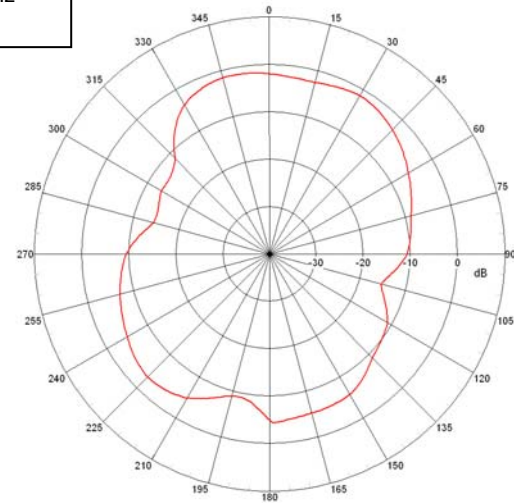
XY-plane @2440MHz
— Total



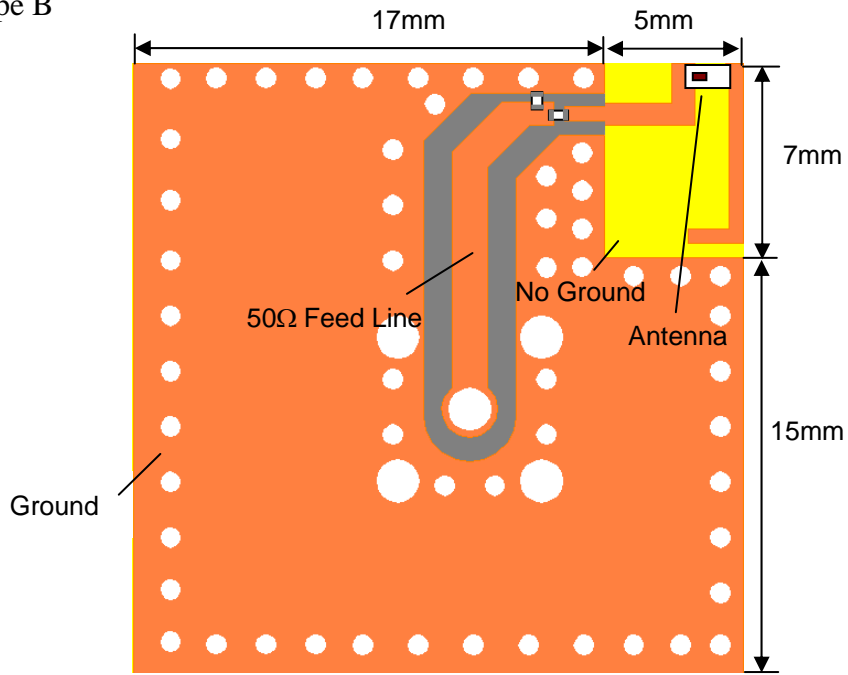
XZ-plane @2440MHz
— Total



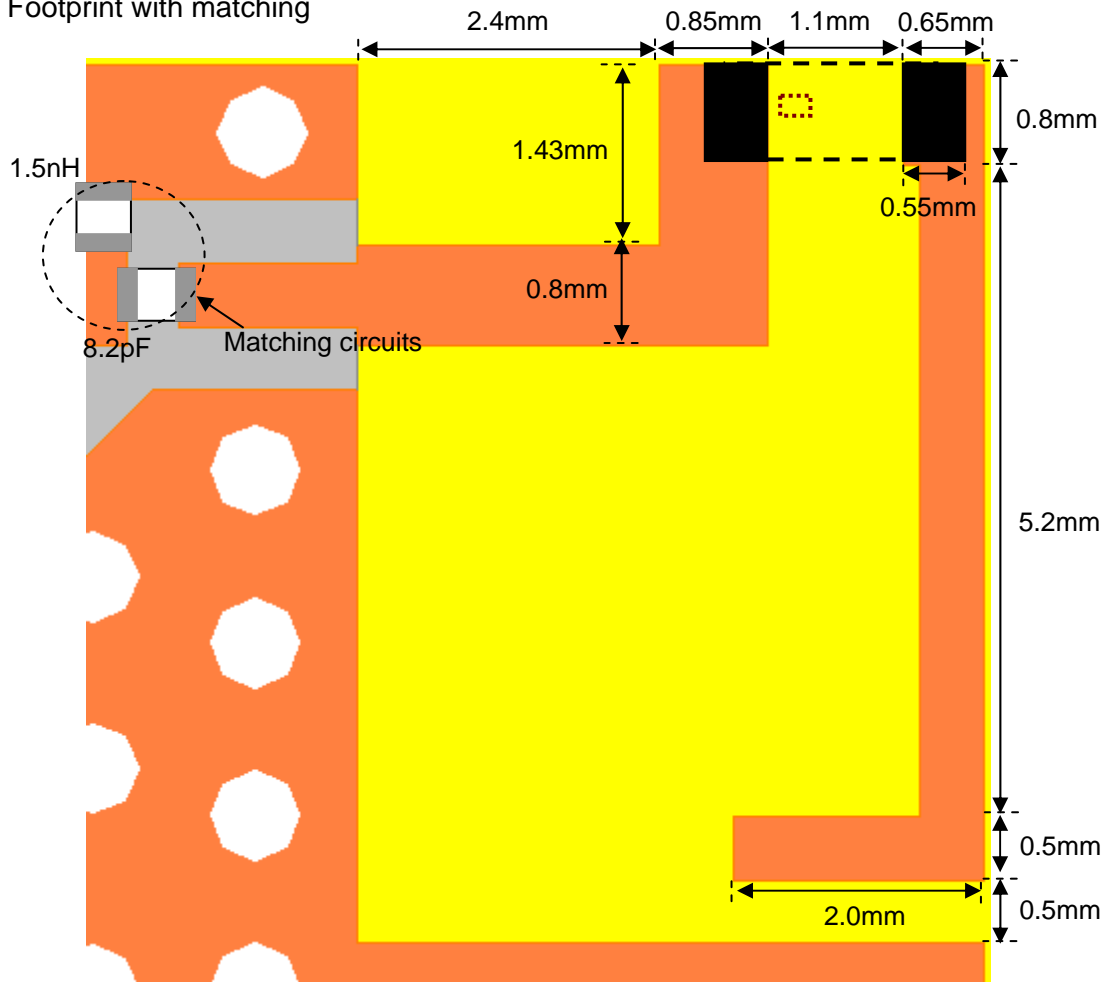
YZ-plane @2440MHz
— Total



❖ Test Board-Type B



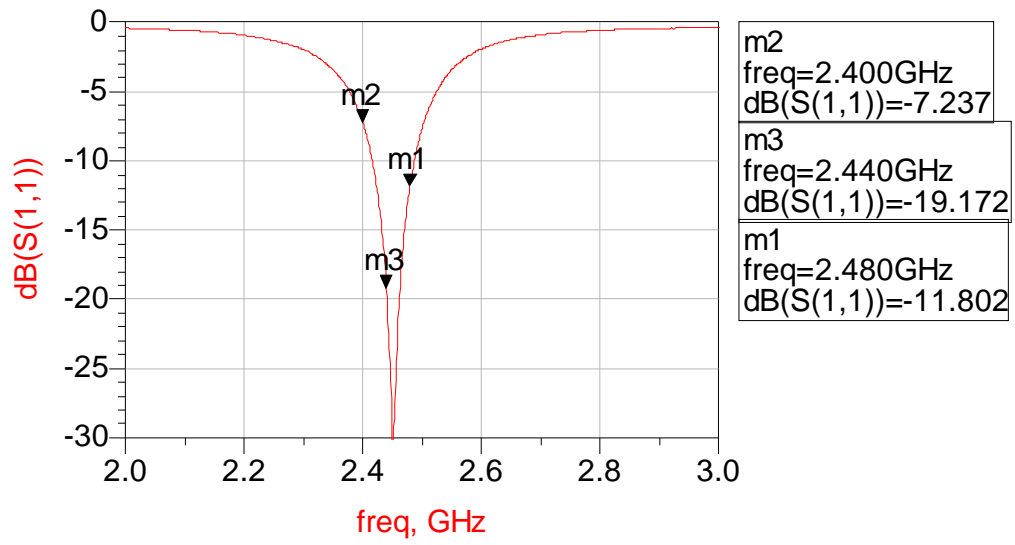
❖ Antenna Footprint with matching



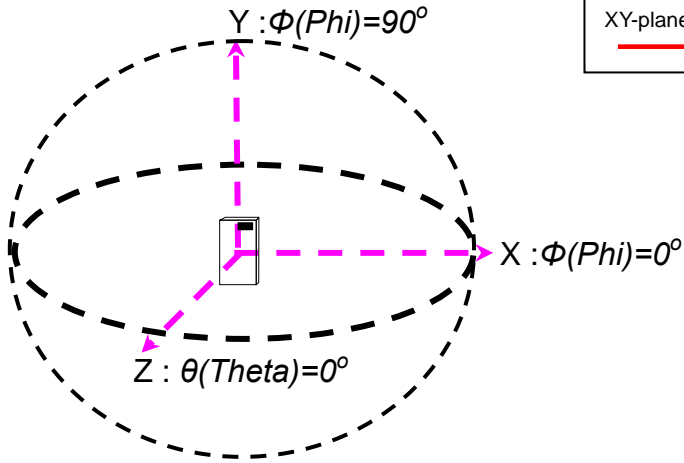
(Matching circuit and component values will be different, depending on PCB layout)

*Line width should be designed to match 50Ω characteristic impedance, depending on PCB material and thickness.

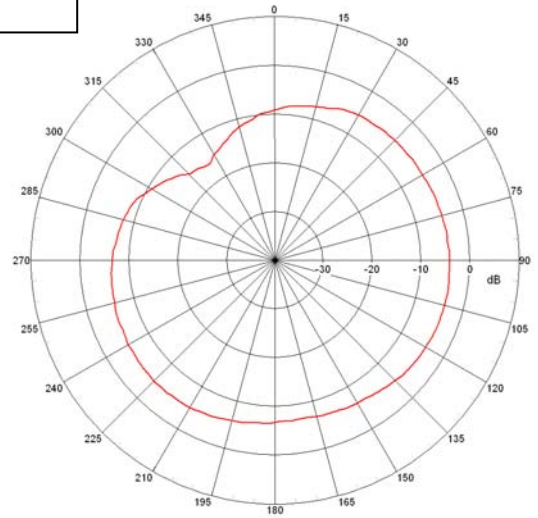
❖ Return Loss (with matching)



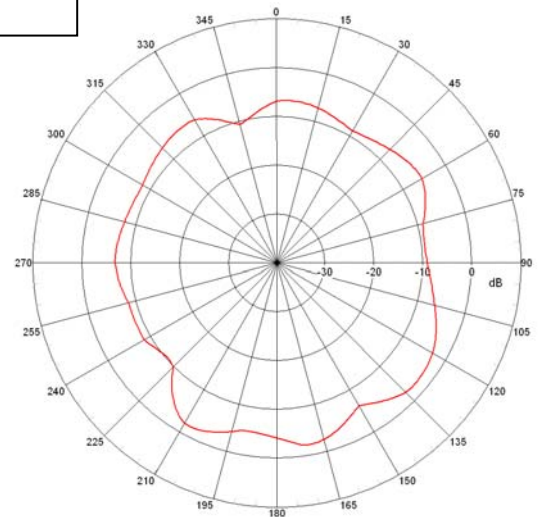
❖ Radiation Patterns- (Antenna Efficiency: 26 %)



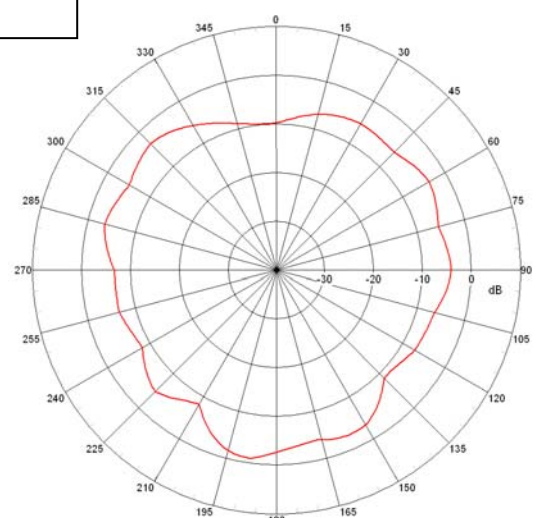
XY-plane @2440MHz
— Total



XZ-plane @2440MHz
— Total

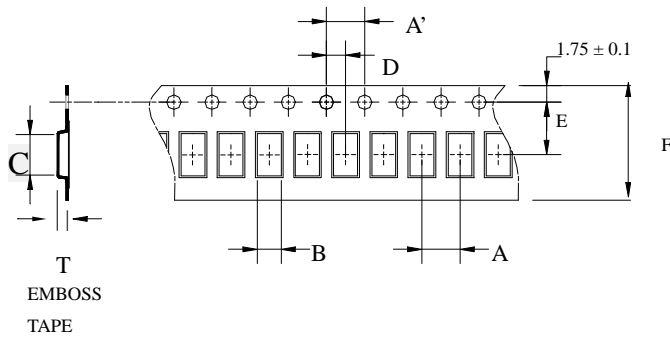


YZ-plane @2440MHz
— Total



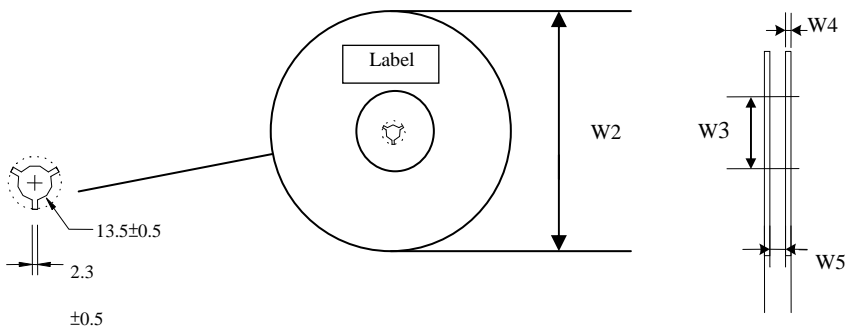
Taping Specifications

❖Tape & Reel Dimensions (Unit: mm) vs. Quantity (pcs)



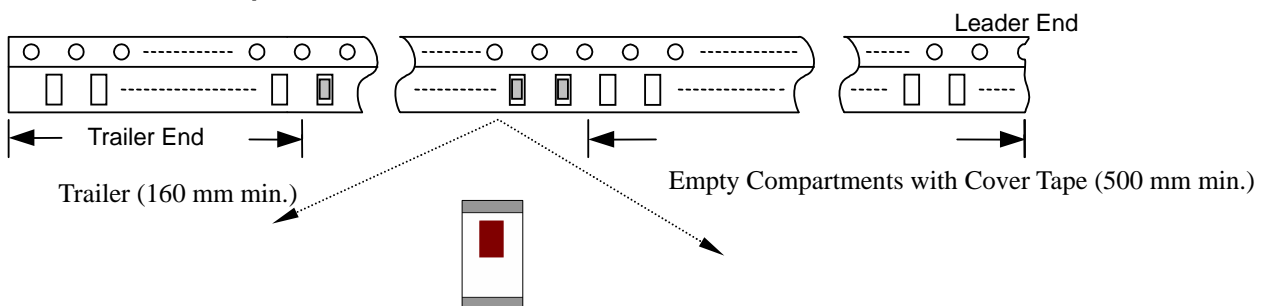
Type	A	A'	B	C	D	E	F	T	Quantity/per reel	Tape material
AT1608	4.0±	4.0±	0.95±	1.80±	2.0±	3.5±	8.0±	0.60±	4,000pcs	Paper
	0.1	0.1	0.1	0.1	0.1	0.1	0.1	0.03		

❖Reel Dimensions (Unit: mm)

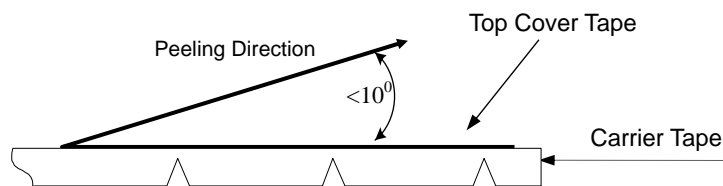


Type	W2	W3	W4	W5
AT1608	178±1	60±1	1.4±0.2	9.0±0.3

❖Leader and Trailer Tape



❖ **Peel-off Force**



Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of 300 ± 10 mm/min .

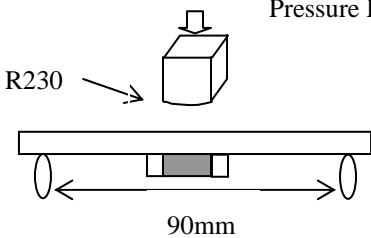
❖ **Storage Conditions**

- (1) Temperature: 5 ~35°C , relative humidity (RH): 45~75%.
- (2) Non-corrosive environment

Notes

❖ The contents of this data sheet are subject to change without notice. Please confirm the specifications and delivery conditions when placing your order.

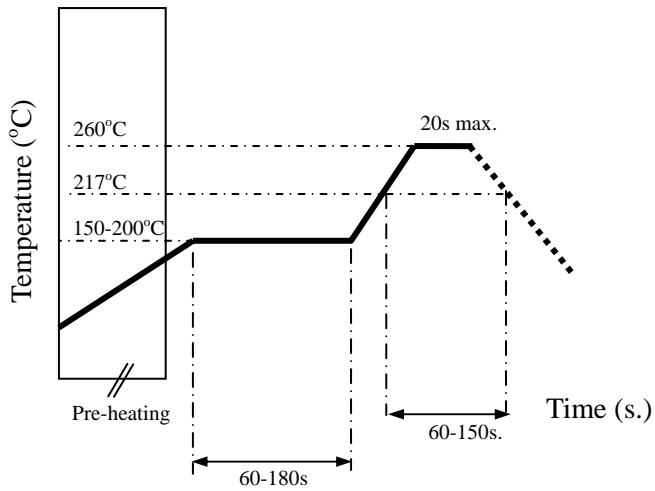
Mechanical & Environmental Characteristics

Item	Requirements	Procedure
Solderability	<ol style="list-style-type: none"> No apparent damage More than 95% of the terminal electrode shall be covered with new solder 	<ol style="list-style-type: none"> Preheat: $120 \pm 5^{\circ}\text{C}$ Solder: $245 \pm 5^{\circ}\text{C}$ for 5 ± 1 sec
Soldering strength (Termination Adhesion)	<ol style="list-style-type: none"> 1kg minimum 	<ol style="list-style-type: none"> Solder specimen onto test jig. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction.
Deflection (Substrate Bending)	<ol style="list-style-type: none"> No apparent damage 	<ol style="list-style-type: none"> Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile. Apply a bending force of 2mm deflection. 
Heat/Humidity Resistance	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> Temperature: $85 \pm 2^{\circ}\text{C}$ Humidity: 90% ~ 95% RH Duration: 1000 ± 48hrs Recovery: 1-2hrs
Thermal shock (Temperature Cycle)	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> One cycle/step 1 : $125 \pm 5^{\circ}\text{C}$ for 30 min step 2 : $-40 \pm 5^{\circ}\text{C}$ for 30 min No of cycles : 100 Recovery: 1-2 hrs
Low Temperature Resistance	<ol style="list-style-type: none"> No apparent damage Fulfill the electrical specification after test 	<ol style="list-style-type: none"> Temperature: $-40 \pm 5^{\circ}\text{C}$ Duration: 500 ± 24hrs Recovery: 1-2hrs

Soldering Conditions

❖ Typical Soldering Profile for Lead-free Process

Reflow Soldering :



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